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ABSTRACT

Method, device, computer-readable storage medium and computer program element for the monitoring of a manufacturing process of a plurality of physical objects

In the case of the method, an analysis is performed by using values of at least one process parameter of the manufacturing process of the physical object and, as a result of the analysis, when they satisfy a prescribed selection criterion, physical objects are marked in such a way that the associated physical objects can be taken as a random sample for the monitoring of the manufacturing process.

List of designations

- 100 — schematic block diagram of a setup of a semiconductor production installation
- 101 — block of an overall manufacturing process
- 102 — block of a first production area
- 103 — block of a second production area
- 104 — block of a third production area
- 105 — block of a fourth production area
- 200 — semiconductor chip production installation
- 201 — multiplicity of semiconductor chip production sub-installations
- 202 — path of a wafer or a lot through the semiconductor chip production installation
- 201 — machine
- 301 — sensor
- 302 — SECS interface
- 303 — PDSF file
- 304 — log file
- 306 — local communication network (LAN)
- 307 — memory
- 308 — evaluation unit
- 409 — mean value of the misalignment values of a lot
- 410 — variation of the distribution
- 411 — wafer close to the mean value of the distribution
- 412 — wafer at the maximum distance from the mean value
- 413 — wafer at the border of the 1σ range of the distribution